



PRODUCT INFORMATION

HIGH TECHNOLOGY MATERIALS

METADUCT 1206

ONE-PART HIGHLY CONDUCTIVE EPOXY COMPOUND FOR ADHESIVE, LAMINATING, AND COATING APPLICATIONS

METADUCT 1206 is a single package epoxy conductive compound ready to use as supplied. Putty-like, and without solvents, volatiles, or reactive diluents, **METADUCT 1206** is easy to use by roller, knifeblade, spatula, or even with dental amalgam carrier. A simple cure schedule converts **METADUCT 1206** to an exceptionally strong, highly conductive, solder-like connective.

No pressure is required for **METADUCT 1206** to bond, laminate or coat ceramics, glass, plastics and metals. It can be used like solder, wherever solder won't work. **METADUCT 1206** may also be used to dissipate heat where high thermal conductivity is required.

Coating with **METADUCT 1206** is done by addition of a solvent such as lacquer thinner, VM&P Naptha, Toluol, etc. The thinned compound may then be applied by brush, spray or dip.

OUTSTANDING FEATURES OF METADUCT 1206

- High electrical conductivity
- No mixing. The hardener is premixed for you.
- High adhesion
- Heat dissipating qualities
- Short cure schedule, only contact pressure required

DIRECTIONS FOR USE

A. AS A CONDUCTIVE ADHESIVE

1. Apply **METADUCT 1206** to one face of mating bond surfaces using a knife or any other convenient applicator. Clean all surfaces of scale and dirt. (For proper preparation of surfaces see MERECO Technical Service Bulletin #3-626).
2. Bring mating parts together. No pressure is required during cure, but parts are best fixtured to prevent shifting.

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3. SUGGESTED CURE SCHEDULES (alternate time and temperature schedules may be used)

<u>TEMP.</u>	<u>GEL TIME</u>	<u>FULL CURE</u>	<u>POST CURE</u>
150°C	30 minutes	60 minutes	2 hours at 125°C
165°C	12 minutes	45 minutes	1 hour at 125°C

An oven or controlled hot plate is recommended for cure, an infrared heat lamp may also be used. Cure of **METADUCT 1206** may also be carried out at temperatures up to 260°C. The parts need to be maintained at this temperature for only 2 to 3 minutes.

B. AS A CONDUCTIVE COATING

1. Mix **METADUCT 1206** with any convenient solvent or solvent mixture such as lacquer thinner, methyl ethyl ketone, toluol or VM&P Naptha and apply by brush, spray, dip or other convenient method.
2. To prevent bubbles, evaporate solvents before curing by drying at room temperature several hours or, alternatively, heating for 2 hours at 85°C. Follow the instructions above for curing.

PROPERTIES OF UNCURED ADHESIVE

Physical form.....	Silver Putty
Specific Gravity.....	2.87
Shelf Life, Months at 25°C.....	4

PROPERTIES OF CURED ADHESIVE

Volume Resistivity, ohm-cm at 25°C.....	0.05
Tensile Shear Strength, 1/2" aluminum lap, psi at 25°C.....	3400
Operating Temperature Range, °C.....	-60 to 185